



Statement of Materials, Construction

Revision: 1.0
Date: 10-Feb-05

LEAD-FREE -- 24L-PDIP -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.47011	Cu	7440-50-8	0.45873	29.12815	97.58
				Fe	7439-89-6	0.01072	0.68059	2.28
				Pb	7439-92-1	0.00000	0.00015	0.0005
				P	7723-14-0	0.00008	0.00537	0.018
				Zn	7440-66-6	0.00059	0.03731	0.125
2	Die	Silicon Chip	0.00621	Si	7440-21-3	0.00621	0.39412	99.95
3	Die attach material	Conductive Epoxy	0.00379	Epoxy resin (5-25)	Proprietary	0.00057	0.03610	15
				Silver (70-85)	7440-21-3	0.00301	0.19132	79.5
				Aromatic Amine (1-10)	Proprietary	0.00021	0.01324	5.5
4	Wire	Gold	0.00079	Au	7440-57-5	0.00079	0.05016	99.99
5	Lead Finish	Tin	0.03178	Sn	7440-31-5	0.03178	2.01793	100
6	Encapsulation	Epoxy Resin	1.0622	Fused Silica	7631-86-9	0.71167	45.18909	67
				Epoxy resin	29690-82-2	0.21244	13.48928	20
				Phenol Resin	9003-35-4	0.07967	5.05848	7.5
				Antimony trioxide	1309-64-4	0.03187	2.02339	3
				Brominated Epoxy Resin	40039-93-8	0.02124	1.34893	2
				Carbon Black	1333-86-4	0.00531	0.33723	0.5
Total Package weight			1.57488					

Note: Composition derived from MSDS and material C of C from Vendors;
 Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%

* Lead is allowed up to 4% as an alloying agent in copper-based alloys